

Supplementary Data

Halogeno-substituted indazoles against copper corrosion in industrial pickling process: A combined electrochemical, morphological and theoretical approach

Yujie Qiang,^a Shengtao Zhang,^{*a} Qin Xiang^a, Bochuan Tan^a, Wenpo Li,^{*a} Shijin Chen^b and Lei Guo^c

^a *School of Chemistry and Chemical Engineering, Chongqing University, Chongqing 400044, China*

^b *Bomin Electronics Ltd., Meizhou 514021, China*

^c *School of Materials and Chemical Engineering, Tongren University, Tongren 554300, China*

Corresponding author.

E-mail address: stzhang_cqu@163.com; *Tel:* +86 23 65678934.

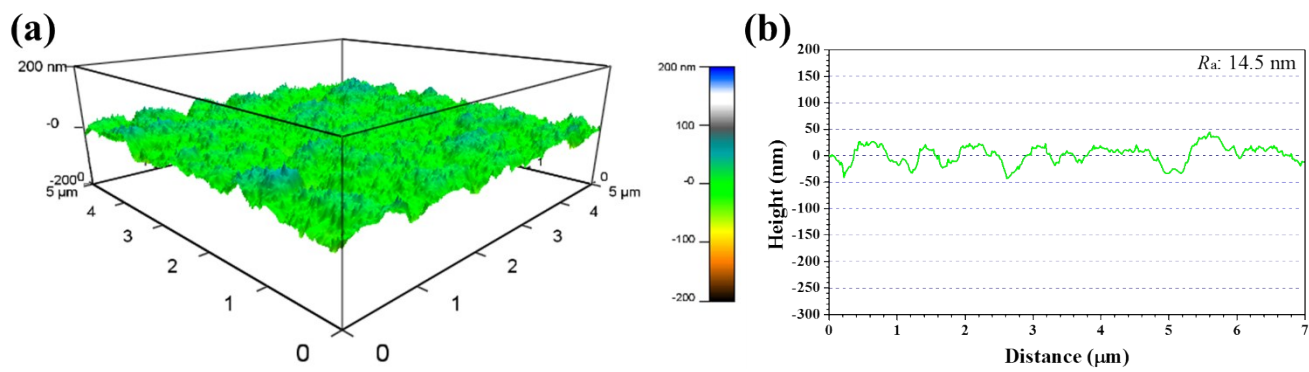


Figure S1 (a) 3D AFM graph and (b) height profile of copper specimen after immersion in 0.5 M H_2SO_4 solution in the presence of 1 mM 4-FIA for 8 h at 298 K.

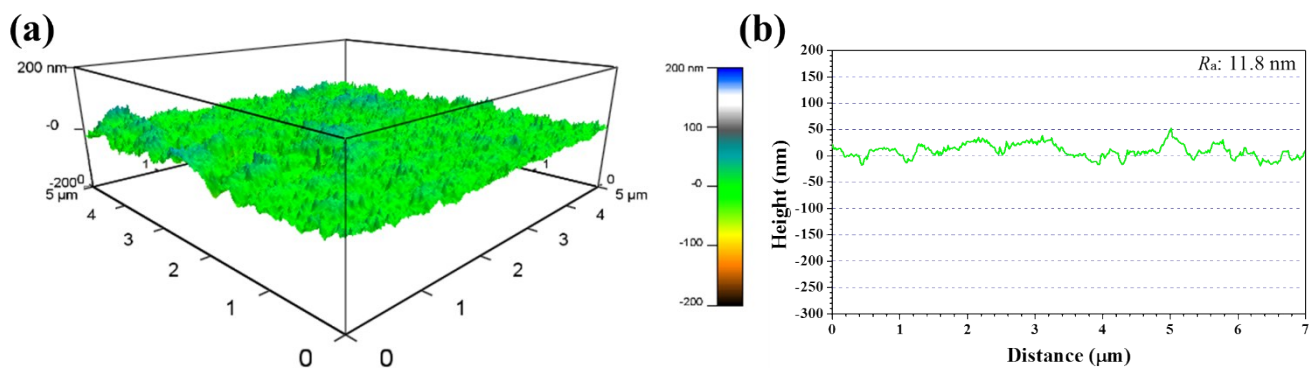


Figure S2 (a) 3D AFM graph and (b) height profile of copper specimen after immersion in 0.5 M H_2SO_4 solution in the presence of 1 mM 4-BIA for 8 h at 298 K.